

## RM50N60TI

# N-Channel Enhancement Mode Power MOSFET

## Description

The RM50N60TI uses advaned trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

- V<sub>DS</sub> =60V,I<sub>D</sub> =50A
  R<sub>DS(ON)</sub> <20mΩ @ V<sub>GS</sub>=10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

#### Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply
- Halogen-free
- P/N suffix V means AEC-Q101 qualified, e.g:RM50N60TIV

#### 100% UIS TESTED!

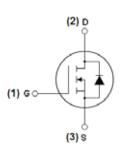
#### 100% \(\Delta Vds TESTED!\)

#### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
50N60	RM50N60TI	TO-220F	-	-	-

#### Absolute Maximum Ratings (T<sub>A</sub>=25<sup>°</sup>Cunless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	VDS	60	V	
Gate-Source Voltage	Vgs	±20	V	
Drain Current-Continuous	Ι <sub>D</sub>	50	A	
Drain Current-Continuous(T <sub>c</sub> =100℃)	l <sub>D</sub> (100℃)	35.4	A	
Pulsed Drain Current	I <sub>DM</sub>	90	A	
Maximum Power Dissipation	PD	85	W	
Dearting factor		0.3	W/℃	
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	245	mJ	
Operating Junction and Storage Temperature Range	TJ,TSTG	-55 To 175	°C	



Schematic diagram



TO-220F top view

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{ extsf{ heta}JC}$	3.3	°C/W

#### Electrical Characteristics (T<sub>c</sub>=25<sup>°</sup>C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	1					1
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	I					
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250µA	1.4	1.9	2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	14	20	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =5V,I <sub>D</sub> =20A	18	-	-	S
Dynamic Characteristics (Note4)	·	•				
Input Capacitance	Clss		-	2050	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V, F=1.0MHz	-	158	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	120	-	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t <sub>d(on)</sub>		-	7.4	-	nS
Turn-on Rise Time	tr	V <sub>DD</sub> =30V, R <sub>L</sub> =6.7Ω	-	5.1	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =10V,R <sub>G</sub> =3Ω	-	28.2	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	5.5	-	nS
Total Gate Charge	Qg	<u>)/ -00)// -004</u>	-	50		nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =30V,I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	6		nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> -10V	-	15		nC
Drain-Source Diode Characteristics	I					
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =20A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	50	A
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, IF =20A	-	28	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>	-	40	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negl	igible (turi	n-on is do	minated b	y LS+LD

#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

**2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.

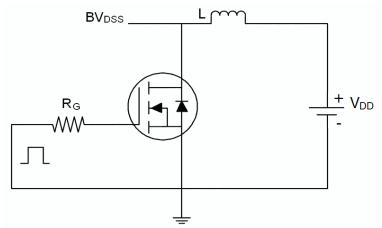
**3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.

4. Guaranteed by design, not subject to production

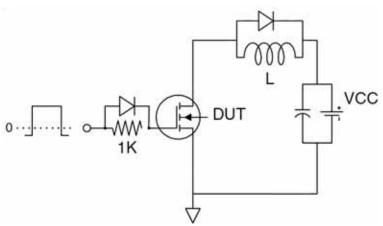
5. EAS condition : Tj=25  $^\circ\!\mathrm{C}$  ,VDD=30V,VG=10V,L=0.5mH,Rg=25 $\Omega$ 



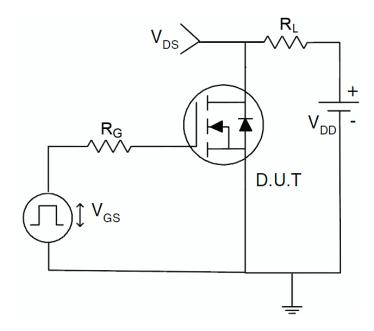
# Test Circuit 1) E<sub>AS</sub> test Circuit



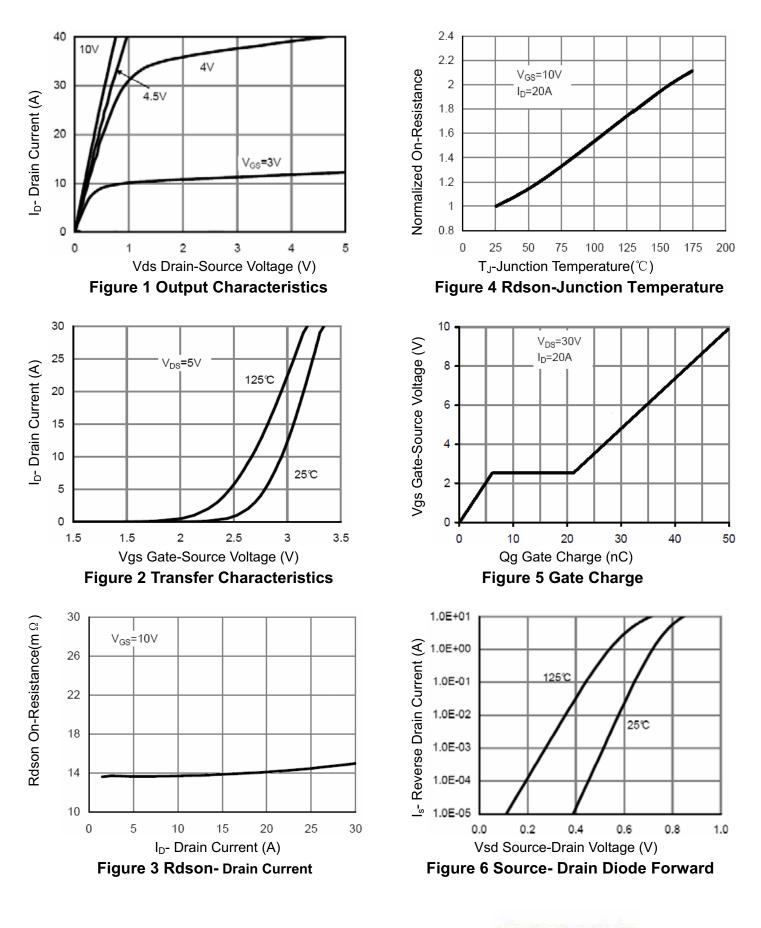
2) Gate charge test Circuit



3) Switch Time Test Circuit







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## RATING AND CHARACTERISTICS CURVES (RM50N60TI)

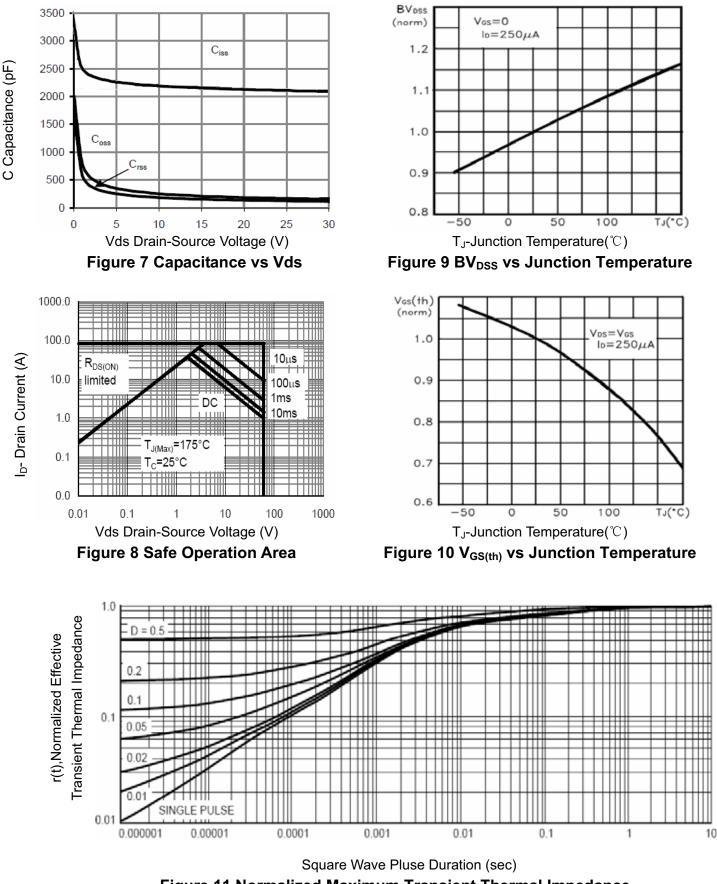
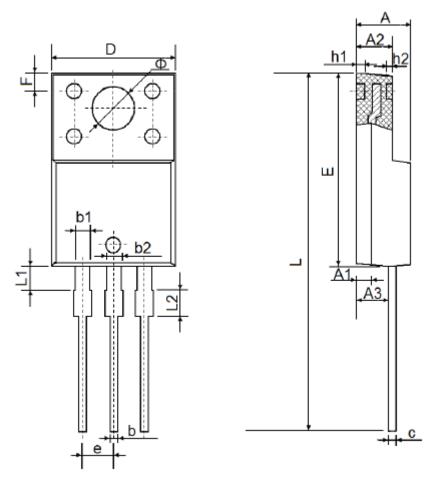


Figure 11 Normalized Maximum Transient Thermal Impedance

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# TO-220F Package Information



Cumhal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.300	4.700	0.169	0.185	
A1	1.30	DREF	0.051	IREF	
A2	2.800	3.200	0.110	0.126	
A3	2.500	2.900	0.098	0.114	
b	0.500	0.750	0.020	0.030	
b1	1.100	1.350	0.043	0.053	
b2	1.500	1.750	0.059	0.069	
с	0.500	0.750	0.020	0.030	
D	9.960	10.360	0.392	0.408	
E	14.800	15.200	0.583	0.598	
е	2.540	)TYP.	0.100	)TYP	
F	2.70	DREF	0.100	GREF	
Φ	3.50	DREF	0.138REF		
h1	0.80	DREF	0.031REF		
h2	0.500REF		0.020REF		
L	28.000	28.400	1.102	1.118	
L1	1.700	1.900	0.067	0.075	
L2	1.900	2.100	0.075	0.083	

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